Product/Process Change Notification

N° 2019-064-A

Dear customer,

please find attached our Infineon Technologies AG PCN:

Several changes affecting TLE75x-ESx products

Important information for your attention:

- Please respond to this PCN by indicating your decision on the approval form, sign it and return to your sales partner before 2021-07-22.
- Infineon aligns with the widely-recognized JEDEC STANDARD "JESD46", which stipulates:
  "Lack of acknowledgement of the PCN within 30 days constitutes acceptance of the change."
  Notwithstanding the aforesaid individual agreements shall prevail.

Your prompt reply will help Infineon to assure a smooth and well-executed transition. If Infineon does not hear from your side by the due date, we will assume your full acceptance to this proposed change and its implementation.

Your attention and response to this matter is greatly appreciated.

On 16 April 2020, Infineon acquired Cypress.
We are now in the process of merging and consolidating our tools and processes for PCN, Information Notes, Errata and Product Discontinuance. We ask for your patience in the meantime. For further details, please visit our website:
https://www.infineon.com/cms/en/about-infineon/company/cypress-acquisition/

Infineon Technologies AG
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Chairman of the Supervisory Board: Dr. Wolfgang Eder
Management Board: Dr. Reinhard Ploss (CEO), Dr. Helmut Gassel, Jochen Hanebeck, Constanze Hufenbecher, Dr. Sven Schneider
Registered Office: Neubiberg
Commercial Register: München HRB 126492

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Products affected Please refer to attached affected product list 1_cip19064_A

Detailed change information

Subject:	Several changes affecting TLE75x-ESx products	
Reason/Motivation:	Change in the pad plating layer and the chip thickness to have a more robust interconnect system. The expansion of the final test location and plating subcontractor will assure continuity of supply enabling flexible manufacturing.	
Description	**Old**	**New**
PROCESS - WAFER PRODUCTION: New final wafer thickness	Wafer thickness: 260 µm	Wafer thickness: 220 µm
PROCESS - WAFER PRODUCTION: New / change of metallization (specifically chip frontside)	Wafer frontside pad metallization: Cu/NiMoP/Pd/Au	Wafer frontside pad metallization: Cu
PROCESS - ASSEMBLY: Move all or parts of production to a different assembly site.	Plating subcontractor: SII Ishizaki (Melaka) Sdn Bhd	Plating subcontractor: SII Ishizaki (Melaka) Sdn Bhd AND Syntronixs (Melaka) Asia Sdn Bhd
TEST FLOW: Move of all or part of electrical wafer test and/or final test to a different test site.	Final test location: Infineon Technologies Asia Pacific Pte. Ltd., Singapore, Singapore	Final test location: Infineon Technologies Asia Pacific Pte. Ltd., Singapore, Singapore AND Infineon Technologies Batam P.T., Batam, Indonesia
Data sheet	Rev. 1.00	Rev. 1.10

Product identification

Traceability assured via date code.
No change in SP ordering number

Anticipated impact of change

Based on the qualification performed, Infineon does not expect any negative impact on quality, function and reliability. No change in fit, form and function expected.

DeQuMa-ID(s): SEM-PW-03 / SEM-PW-07 / SEM-PA-18 / SEM-TF-01

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Attachments

1_cip19064_A	affected product list
4_cip19064_A	data sheets

Time schedule

Final qualification report	available
First samples available	on request
Intended start of delivery [1]	2021-12-15
Last order date (LOD) [2]	2021-12-15
Last delivery date (LDD) [3]	2022-06-15

[1] provided date or earlier after customer approval
[2] Last time buy volume to be placed latest until LOD
[3] Delivery of new product can be earlier (see Intended start of delivery) and depends on approval

If you have any questions, please do not hesitate to contact your local sales office.